

QFN0404-24C Power Dissipation (105°C)

Power dissipation data for the QFN0404-24C is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

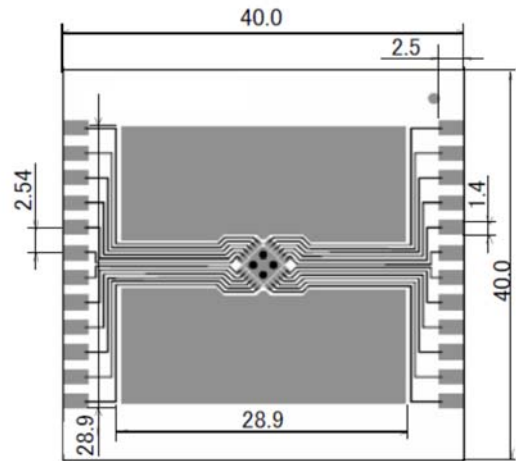
Boards Dimensions : 40 x 40 mm (1600 mm²)

Board Structure: 4 Copper Layers Each layer is 50% connected
To the package heat-sink.

Material : Glass Epoxy (FR-4)

Thickness : 1.0mm

Through-hole : 4 x 0.4 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1500	66.67
105	300	

